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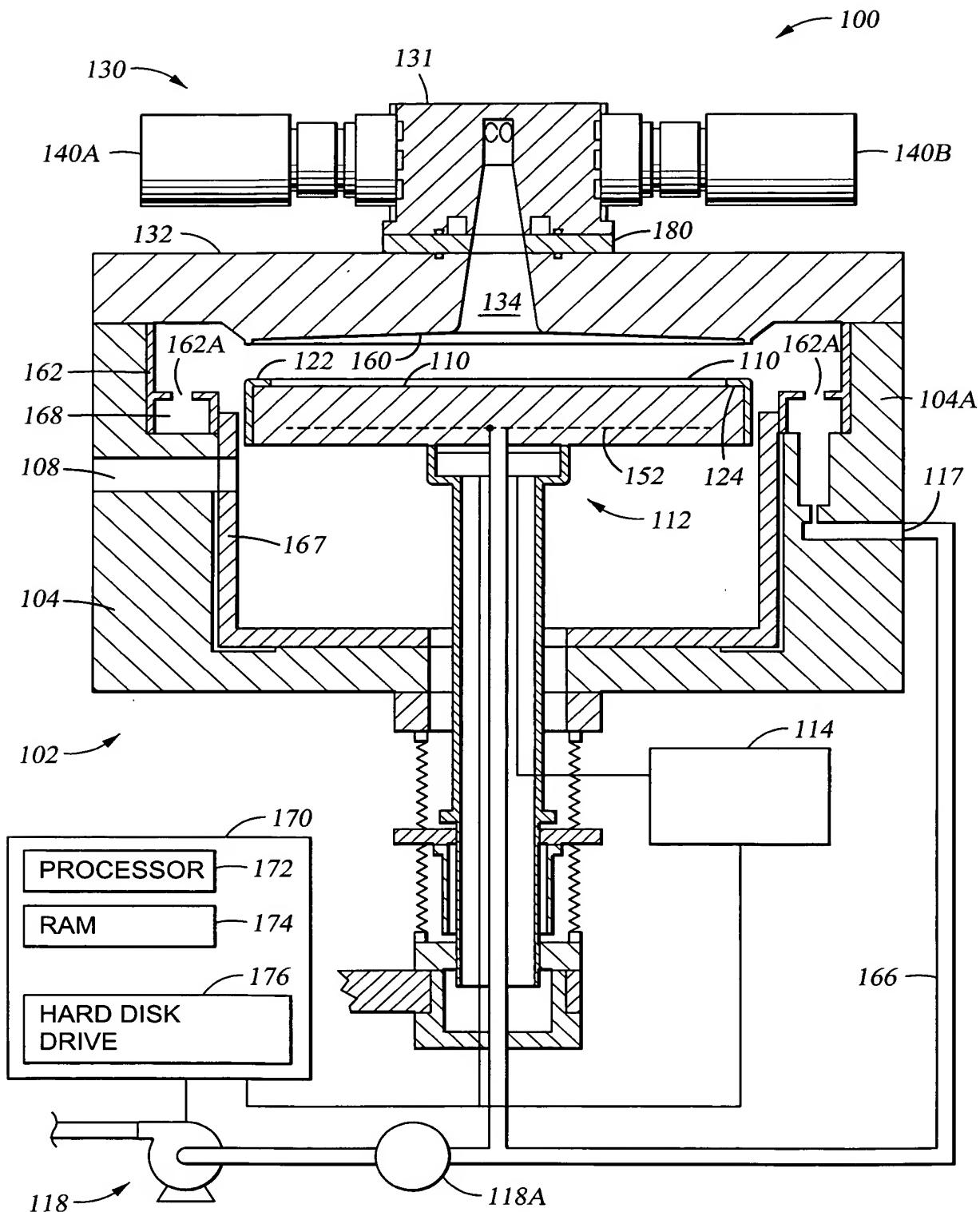


Fig. 1

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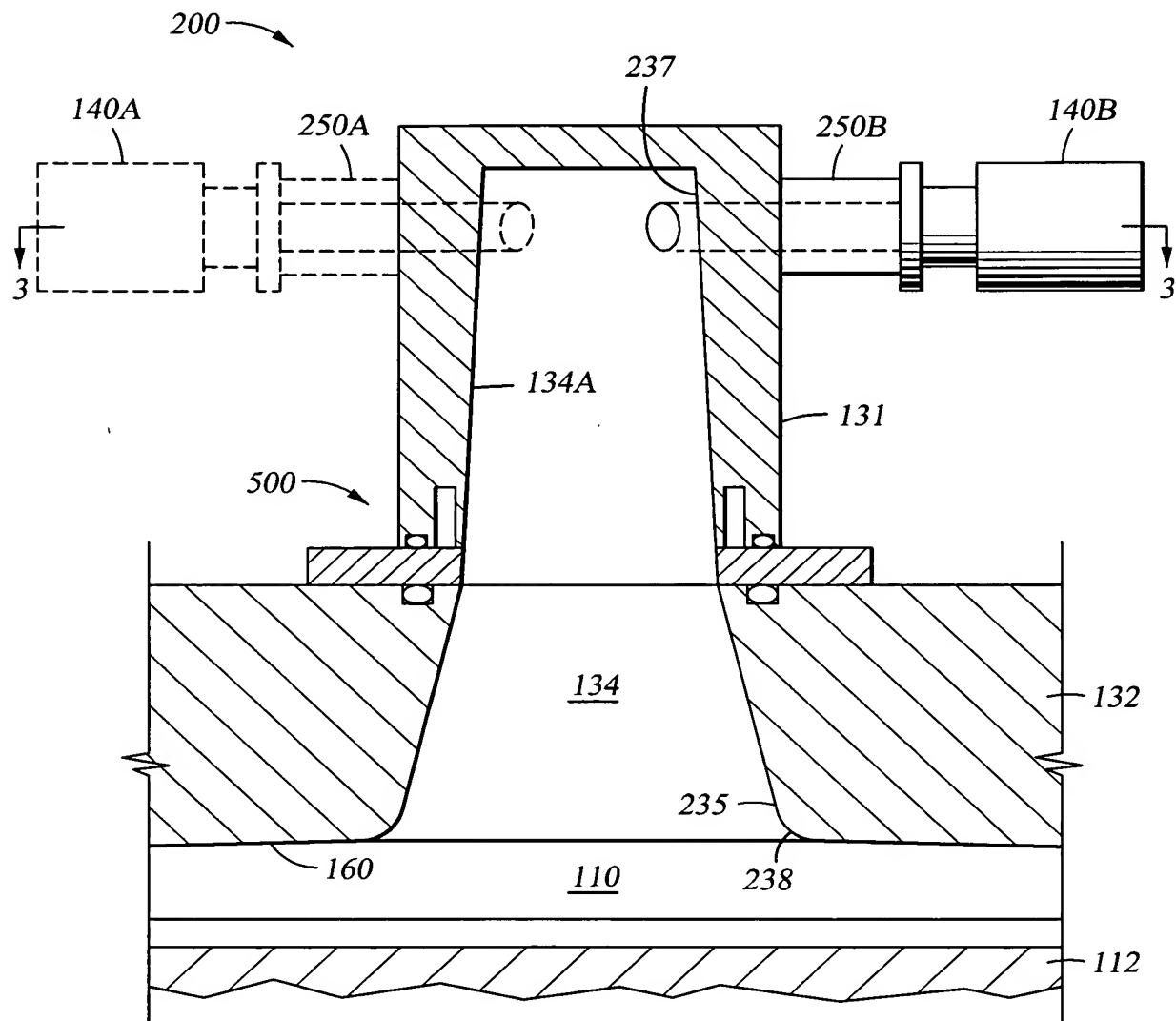


Fig. 2

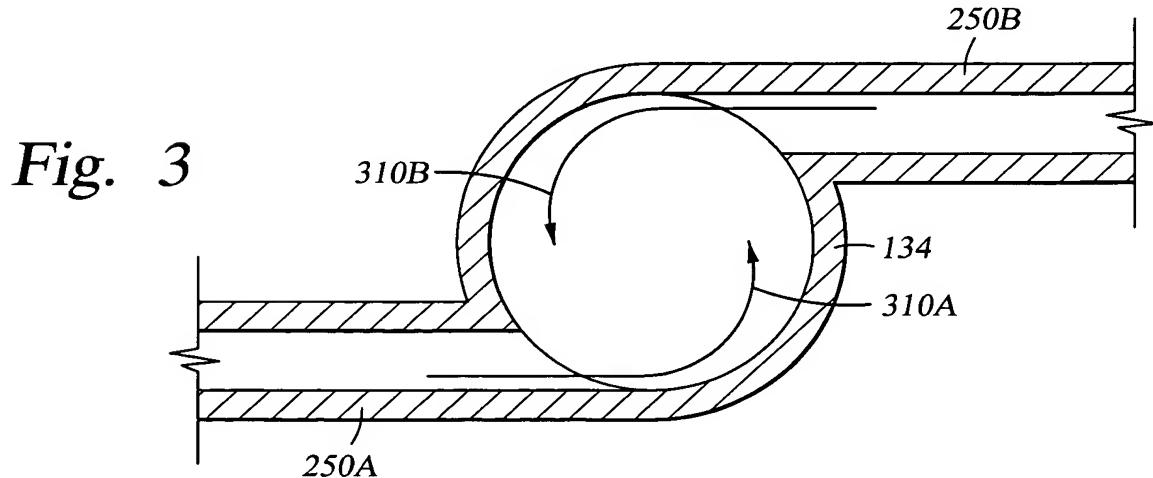


Fig. 3

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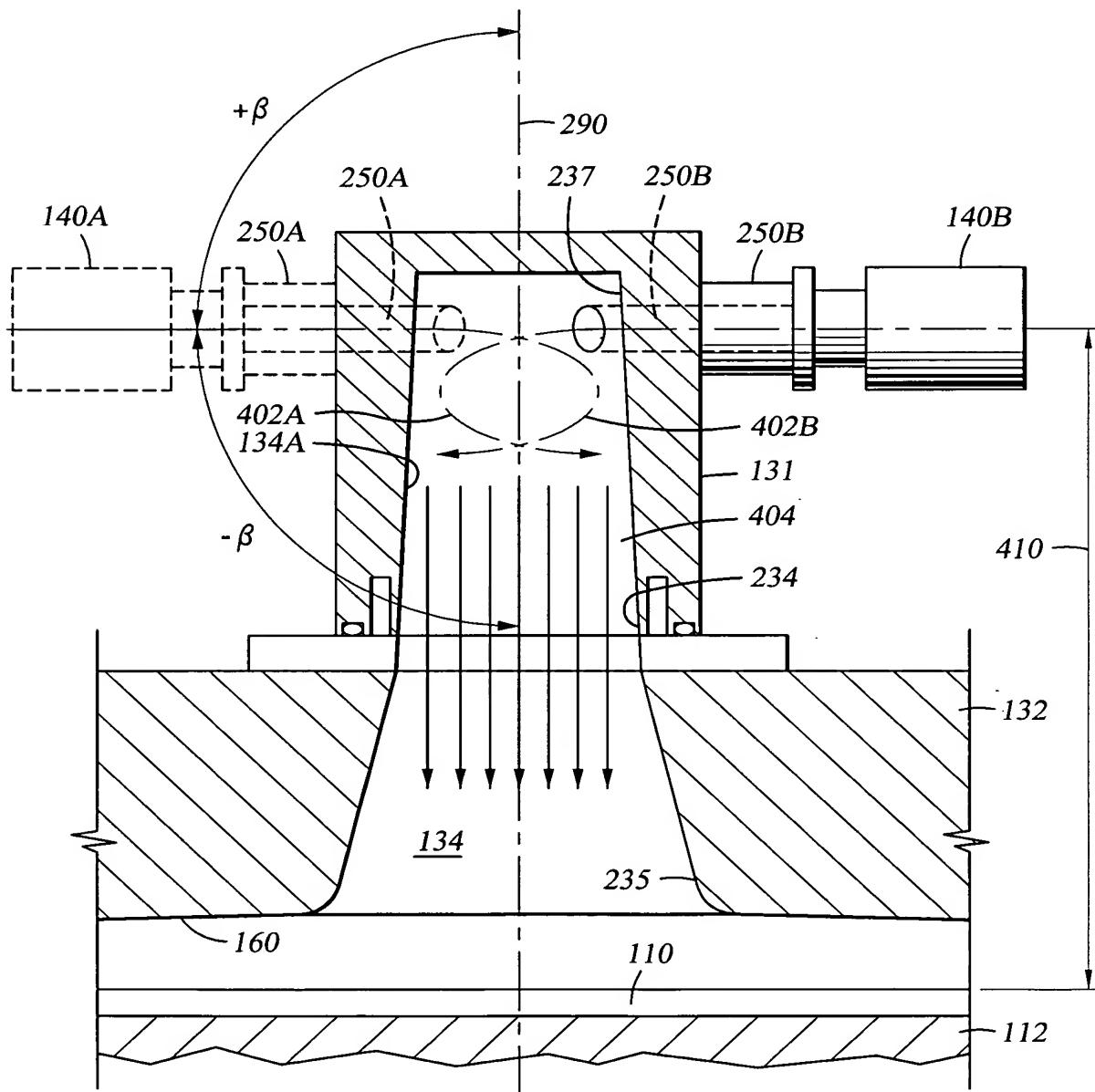


Fig. 4

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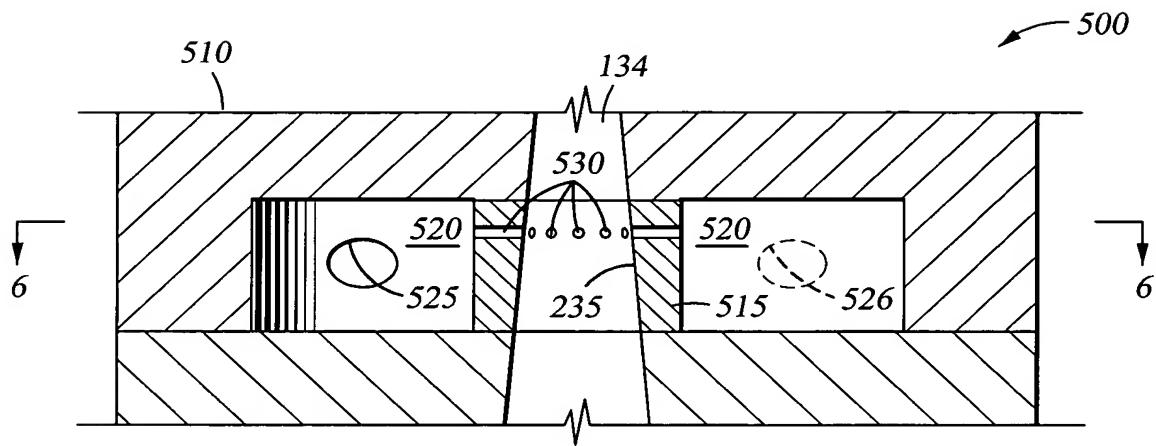


Fig. 5A

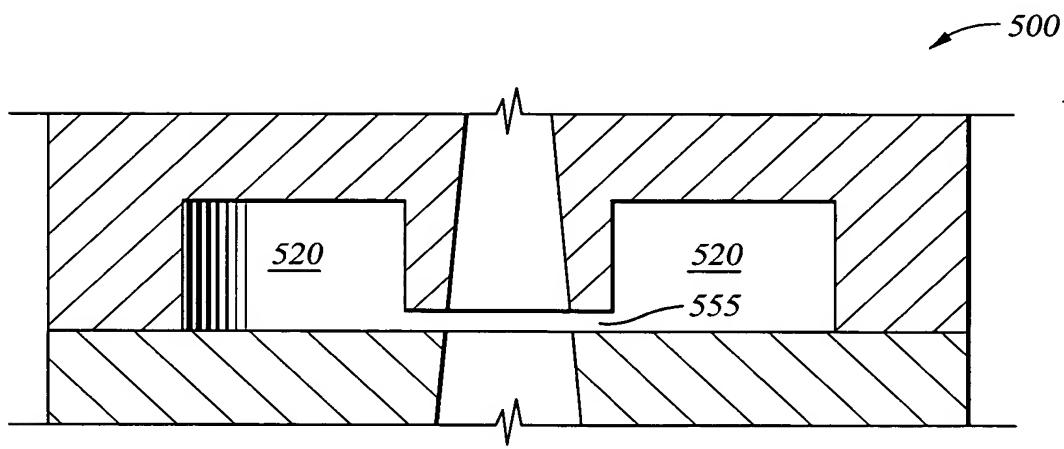


Fig. 5B

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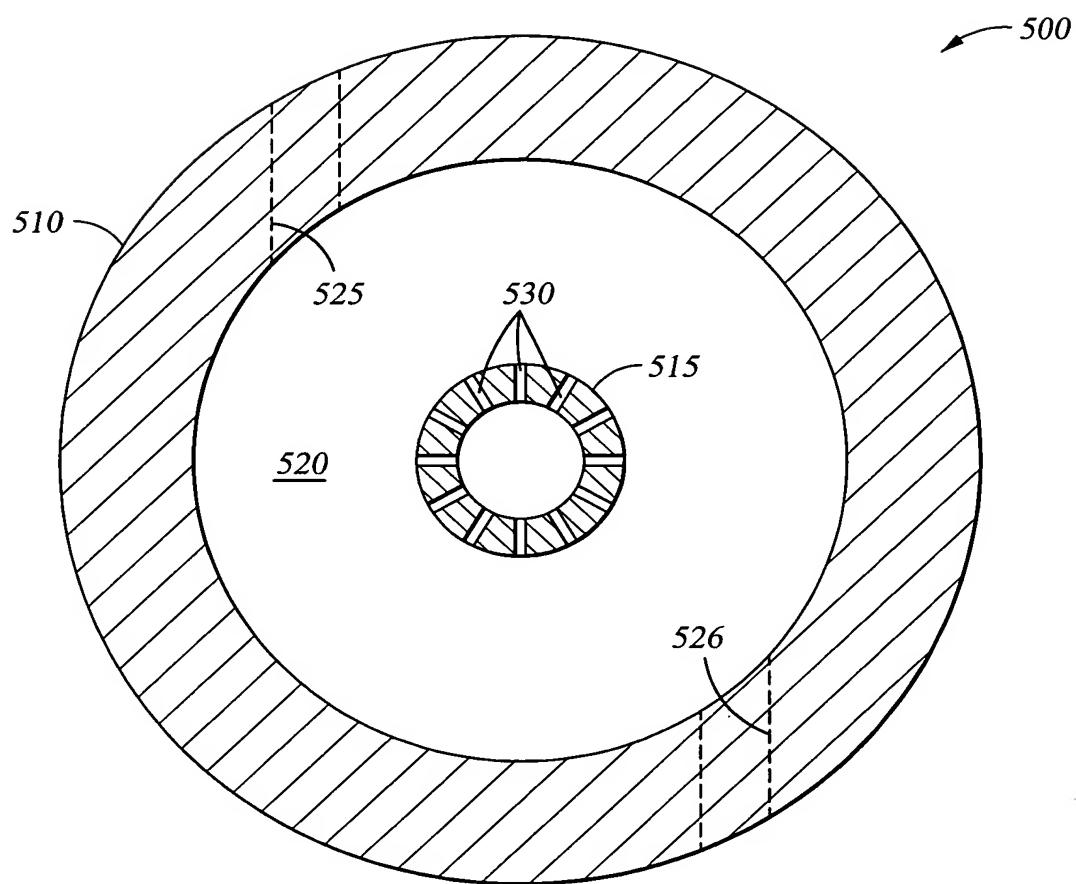


Fig. 6

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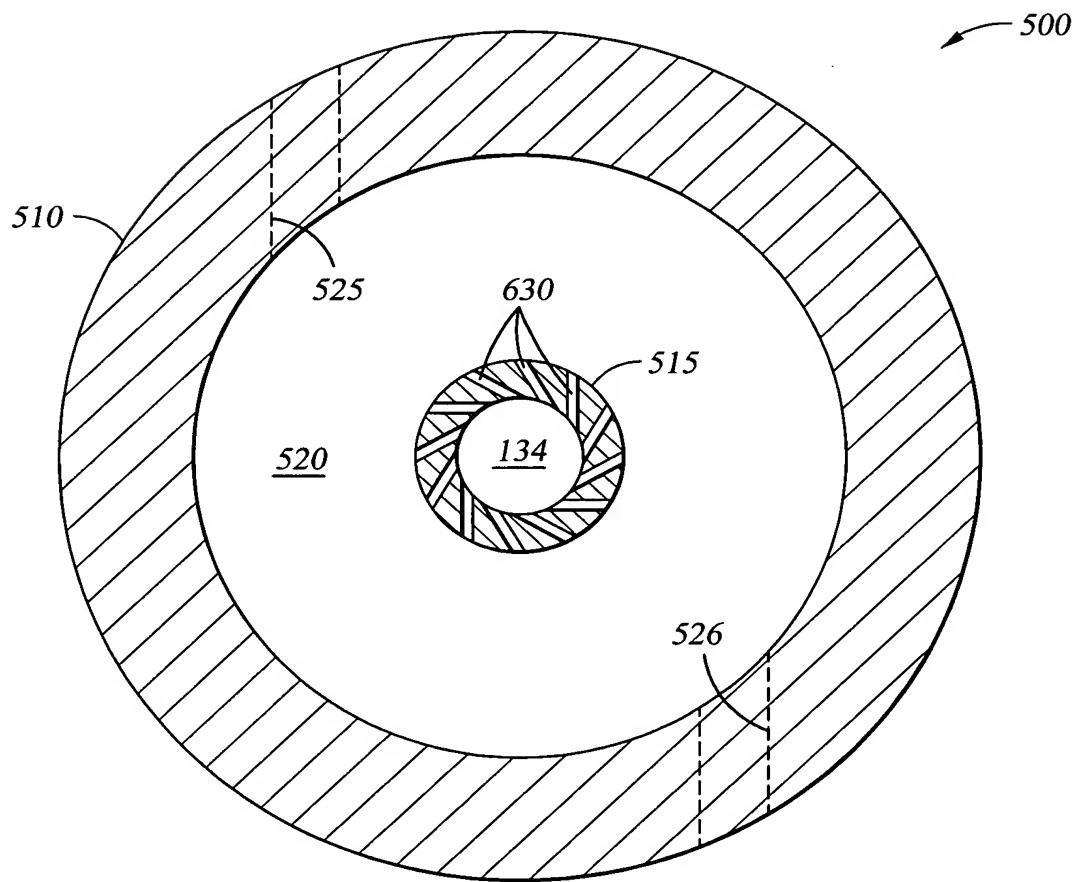


Fig. 6A

ATTY DKT. No.: AMAT/6766/CPI/L/B/PJS
U.S. SERIAL No.: TO BE ASSIGNED
FILED:
APPLICANT: HEREWITH
TITLE: APPLIED MATERIALS, INC.
PROCESSING
INVENTOR: LING CHEN, ET AL.
EXPRESS MAIL No.: EV 335470348 US

CONF. No.: }

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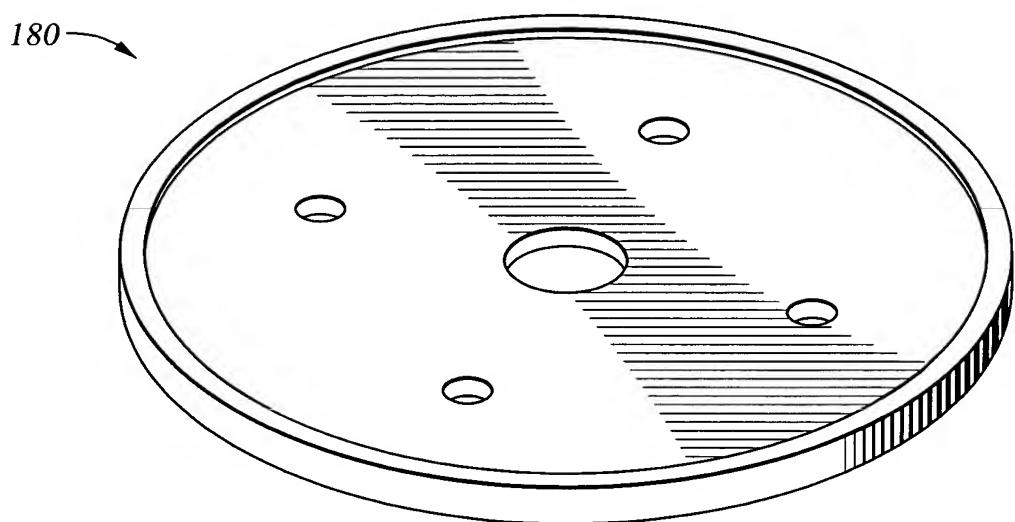


Fig. 7

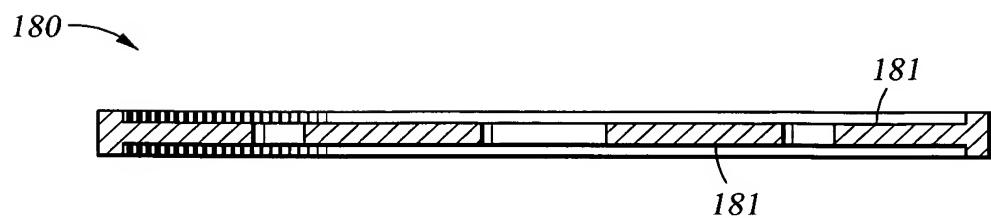


Fig. 7A

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Fig. 8A

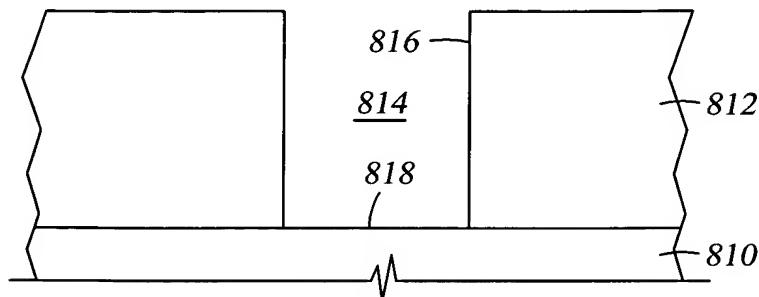


Fig. 8B

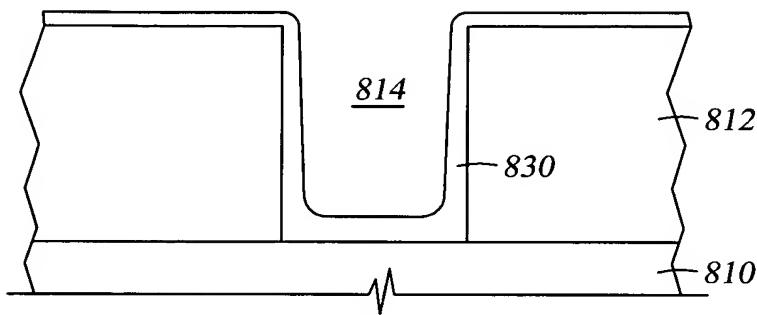


Fig. 8C

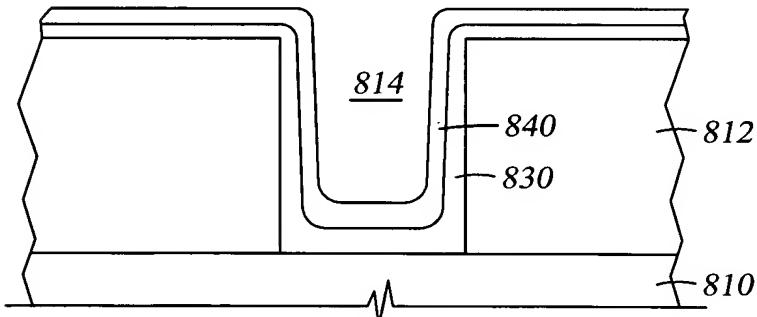
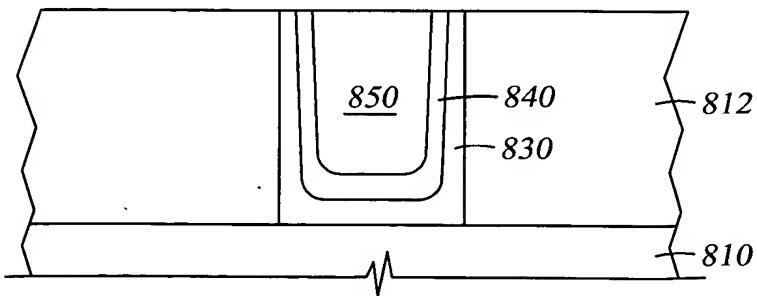


Fig. 8D



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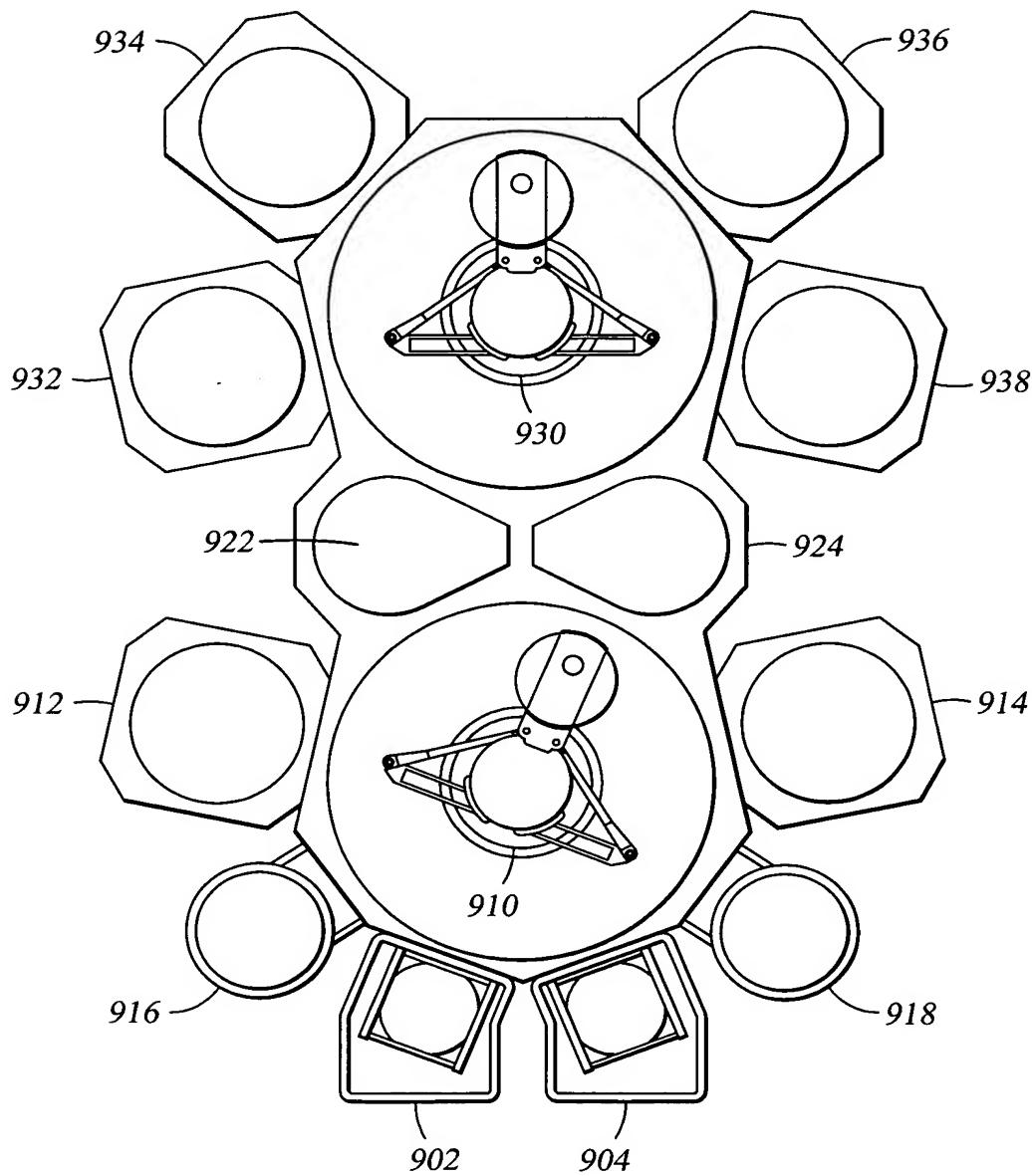


Fig. 9